



Initial Product/Process Change Notification

Document #: IPCN25009X

Issue Date: 07 Nov 2022

Title of Change:	MicroPak 6lds and MicroPak 8lds Assembly and Test Site Addition				
Proposed First Ship date:	01 Apr 2023 or earlier if approved by customer				
Contact Information:	Contact your local onsemi Sales Office or logic.fpcn@onsemi.com				
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.				
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>				
Marking of Parts/ Traceability of Change:	The new assembly site marking is S				
Change Category:	Test Change, Assembly Change				
Change Sub-Category(s):	Manufacturing Site Addition				
Sites Affected:					
onsemi Sites			External Foundry/Subcon Sites		
None			STARS Microelectronics, Thailand		
Description and Purpose:					
A new Subcon site was qualified to increase back end capacity.					
There is no change in form, fit and function except the marking of plant code.					
FXLH1T45L6X					
	From			To	
Assembly Site	UTAC	Hana	UTAC	Hana	STARS
LeadFrame	LF UDFN 6L C7025 1.45X1MM ETCHED PP	LF UDFN 6L C7025 Cu COL 1.45X1.0 ETCHED UPPF	LF UDFN 6L C7025 1.45X1MM ETCHED PP	LF UDFN 6L C7025 Cu COL 1.45X1.0 ETCHED UPPF	PPF RT UPG (MicroPak 1.45 x1 6 lds)
Die Attach	DA AB 8006NS 10CC	DA EPOXY HE ABLEBOND 8006NS 10CC 14G NON CON	DA AB 8006NS 10CC	DA EPOXY HE ABLEBOND 8006NS 10CC 14G NON CON	HR-5104
Mold Compound	SUMITOMO G770HCD	MC CEL9220HF13H HF	SUMITOMO G770HCD	MC CEL9220HF13H HF	Sumitomo EME G700LTD



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FXMA2102L8X and FXWA9306L8X

	From	To	
Assembly Site	Hana	Hana	STARs
LeadFrame	LF UQFN 8L C7025 Cu 1.6X1.6 ETCHED UPPF	LF UQFN 8L C7025 Cu 1.6X1.6 ETCHED UPPF	PPF RT UPG (MicroPak 1.6x1.6 8lds)
Die Attach	DA EPOXY HE ABLEBOND 8006NS 10CC 14G NON CON	DA EPOXY HE ABLEBOND 8006NS 10CC 14G NON CON	HR-5104
Mold Compound	MC CEL9220HF13H HF	MC CEL9220HF13H HF	Sumitomo EME G700LTD

Qualification Plan:

QV DEVICE NAME: FXLH1T45L6X (unbiased) FXMA2102L8X (biased)

RRF: O83395

PACKAGE: SIP6 | uQFN8

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta= 125°C	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	
PD	JESD22-B100 and JESD22-B108	Per Case Outline	
SD	JSTD002	Ta = 245C, 5 sec	

QV DEVICE NAME: FXMA2102L8X

RRF: O83395

PACKAGE: uQFN8

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta= 125°C	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	
PD	JESD22-B100 and JESD22-B108	Per Case Outline	
SD	JSTD002	Ta = 245C, 5 sec	

Estimated date for qualification completion: 31 January 2023

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FXWA9306L8X	FXMA2102L8X



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FXMA2102L8X	FXMA2102L8X
FXLH1T45L6X	FXLH1T45L6X

Appendix A: Changed Products

PCN#: IPCN25009X
Issue Date: Nov 06, 2022

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
FXWA9306L8X		FXMA2102L8X	NA	
FXLH1T45L6X		FXLH1T45L6X	NA	
FXMA2102L8X		FXMA2102L8X	NA	